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Substitute for 37 CFR 1.418(a) PTO Form 261 <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (use as many sheets as necessary)		<b>Complete If Known</b>			
		Application Number	09/773,522		
		Filing Date	February 20, 2001		
		First Named Inventor	Paul A. Farrar		
		Group Art Unit	N/A		
		Examiner Name	Not Yet Assigned		
Sheet	2	of	2	Attorney Docket Number	M4065.0392/P392

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
BT	L	Solder Transfer Technique for Flip-Chip and Electronic Assembly Applications, Karl J. Puttlitz, et al., IEEE Transactions on Components, Packaging and Manufacturing Technology, Part C, Vol. 21, No. 3, July, 1998.	
	M	MicroJet Printing of Solder and Polymers for Multi-Chip Modules and Chip-Scale Packages, Donald J. Hayes et al., MicroFab Technologies, Inc., IMPAS '99.	
	N	Self-Aligned Controlled Collapse Chip Connect (SAC4), L. Pfeiffer et al., J. Electrochem. Soc.: Solid-State Science and Technology, November 1987.	
	O	Review of Flip Chip Bonding, Vincent C. Marcotte, et al., IBM East Fishkill Facility.	
	P	Solder Jet Printing of Micropads and Vertical Interconnects, David B. Wallace, et al., www.microfab.com/paper/smta97/smta97.htm, (8/12/00).	
	Q	Combination Process for Final Metal Lines and Metal Terminals, Research Disclosure, No. 34232, Kenneth Mason Publications Ltd., England (October 1992/753).	
	R	Process for High Density of Chip Terminals on Large Wafers, Research Disclosure, 34625 Kenneth Mason Publications Ltd., England (February 1993/97).	
	S	Key Process Controls for Underfilling Flip Chips, Alec J. Babiarz et al., Solid State Technology, 1997 by PennWell Publishing Company.	
	T	Mark's Standard Handbook for Mechanical Engineers, Tenth Edition, Eugene A. Avallone, et al.	
	U	Flow of gases through tubes and orifices, David G. Worden, Scientific Foundations of Vacuum Technique, Saul Dushman.	
	V	Sorption of gases by "active" charcoal, silicates (including glasses), and cellulose, "Scientific Foundations of Vacuum Technique", J. Wiley and Sons (1962).	
	W	Electronic Materials Handbook, Vol. 1, Packaging, pages 301, 440.	
BT	X	Technology Challenges for Advanced Interconnects, James G. Ryan et al, Conference Proceedings ULSI XIII@1998 Materials Research Study.	

Examiner Signature	B. Talbot	Date Considered	3/28/03
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<sup>1</sup>EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>2</sup>Unique citation designation number. <sup>3</sup>Applicant is to place a check mark here if English language Translation is attached